

## P-Channel 30V(D-S) MOSFET

Product summary		
$V_{DS}$	-30	V
$R_{DS(ON)}$ (at $V_{GS}=-10V$ ) Typ.	9.5	$m\Omega$
$R_{DS(ON)}$ (at $V_{GS}=-4.5V$ ) Typ.	14	$m\Omega$
$I_D(T_A=25^\circ C)$	-12	A

### Features

- High density cell design for low  $R_{DS(ON)}$
- Trench Power LV MOSFET technology
- High Speed switching

### Applications

- Power management functions
- Load switch

### Pin Configuration



### Packing Information

Device	Package	Reel Size	Quantity(Min. Package)
ECG4407	SOP8	13 "	4000pcs

### Absolute Maximum Ratings (at $T_A=25^\circ C$ Unless Otherwise Noted)

Symbol	Parameter	Rating	Units
$V_{DS}$	Drain-Source Voltage	-30	V
$V_{GS}$	Gate-Source Voltage	$\pm 25$	V
$I_D$	Continuous Drain Current <sup>A</sup>	$-12$	A
		$-10$	A
$I_{DM}$	Pulse Drain Current <sup>B</sup>	-55	A
$E_{AS}$	Single Pulse Avalanche Energy <sup>C</sup>	105	mJ
$P_D$	Power Dissipation <sup>A</sup>	3.2	W
$T_J, T_{STG}$	Junction and Storage Temperature Range	-55 to +150	°C

### Thermal Characteristics

Symbol	Parameter	Typical	Units
$R_{\theta JA}$	Thermal Resistance-Junction to ambient <sup>A</sup>	39	°C/W

Electrical Characteristics (at  $T_J = 25^\circ\text{C}$  Unless Otherwise Noted)

Symbol	Parameter	Condition	Min.	Typ.	Max.	Units
<b>Static Parameters</b>						
$\text{BV}_{\text{DSS}}$	Drain-Source Breakdown Voltage	$V_{\text{GS}}=0\text{V}, I_{\text{D}}=-250\mu\text{A}$	-30	--	--	V
$I_{\text{DSS}}$	Zero Gate Voltage Drain Current	$V_{\text{DS}}=-30\text{V}, V_{\text{GS}}=0\text{V}$	--	--	-1	$\mu\text{A}$
$I_{\text{GSS}}$	Gate-Body Leakage Current	$V_{\text{DS}}=0\text{V}, V_{\text{GS}}=\pm 25\text{V}$	--	--	$\pm 100$	nA
$V_{\text{GS}(\text{th})}$	Gate Threshold Voltage	$V_{\text{DS}}=V_{\text{GS}}, I_{\text{D}}=-250\mu\text{A}$	-1.2	-1.8	-2.8	V
$R_{\text{DS}(\text{ON})}$	Drain-Source On-State Resistance <sup>B</sup>	$V_{\text{GS}}=-20\text{V}, I_{\text{D}}=-12\text{A}$	--	9.0	10.5	$\text{m}\Omega$
		$V_{\text{GS}}=-10\text{V}, I_{\text{D}}=-12\text{A}$	--	9.5	12.5	$\text{m}\Omega$
		$V_{\text{GS}}=-4.5\text{V}, I_{\text{D}}=-10\text{A}$	--	14	21	$\text{m}\Omega$
$V_{\text{SD}}$	Diode Forward Voltage	$I_{\text{S}}=-12\text{A}, V_{\text{GS}}=0\text{V}$	--	--	-1.2	V
<b>Dynamic Parameters <sup>D</sup></b>						
$C_{\text{iss}}$	Input Capacitance	$V_{\text{GS}}=0\text{V}, V_{\text{DS}}=-15\text{V}$ $f=1\text{MHz}$	--	2152	--	pF
$C_{\text{oss}}$	Output Capacitance		--	308	--	pF
$C_{\text{rss}}$	Reverse Transfer Capacitance		--	242	--	pF
$Q_g$	Total Gate Charge	$V_{\text{DS}}=-15\text{V}, I_{\text{D}}=-12\text{A}$ $V_{\text{GS}}=-10\text{V}$	--	40.1	--	nC
$Q_{\text{gs}}$	Gate-Source Charge		--	8.4	--	nC
$Q_{\text{gd}}$	Gate-Drain Charge		--	8.6	--	nC
$t_{\text{D}(\text{on})}$	Turn-on Delay Time	$V_{\text{DD}}=-15\text{V}$ $I_{\text{D}}=-1\text{A}, R_{\text{G}}=2.5\Omega$ , $V_{\text{GS}}=-10\text{V}$	--	8	--	ns
$t_r$	Turn-on Rise Time		--	19	--	ns
$t_{\text{D}(\text{off})}$	Turn-off Delay Time		--	75	--	ns
$t_f$	Turn-off Fall Time		--	46	--	ns
$t_{\text{rr}}$	Reverse recovery time	$I_{\text{F}}=-12\text{A}$ , $di/dt=100 \text{ A/uS}$	--	18	--	ns
$Q_{\text{rr}}$	Reverse recovery charge		--	7.8	--	nC

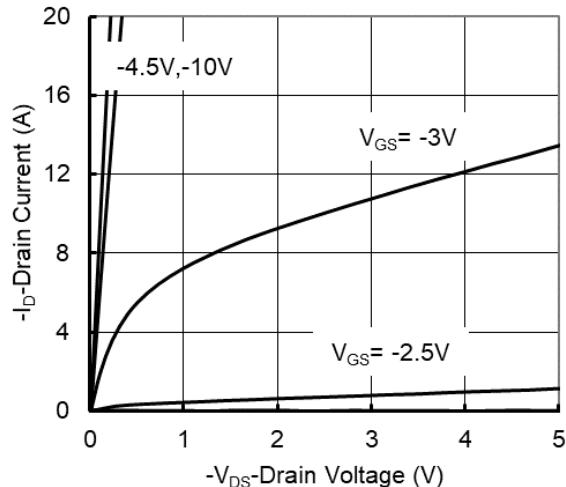
A. The data tested by surface mounted on a 1 inch<sup>2</sup> FR-4 board with 2OZ copper.

B. The data tested by pulsed , pulse width $\leq 300\mu\text{s}$  , duty cycle $\leq 2\%$ .

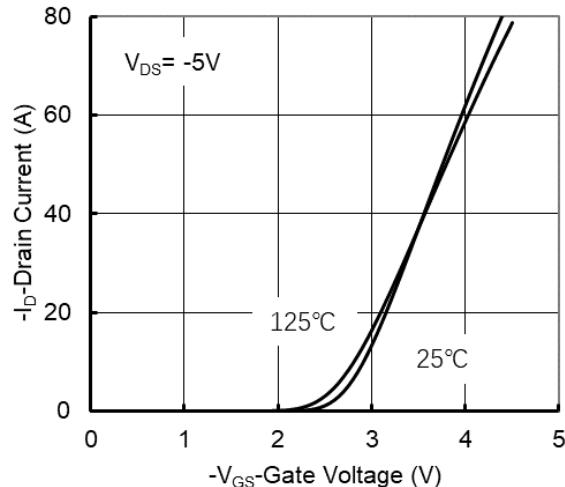
C.The EAS data shows Max. rating . The test condition is  $L=0.3\text{mH}, T_A=25^\circ\text{C}$ .

D. Guaranteed by design, not subject to production testing.

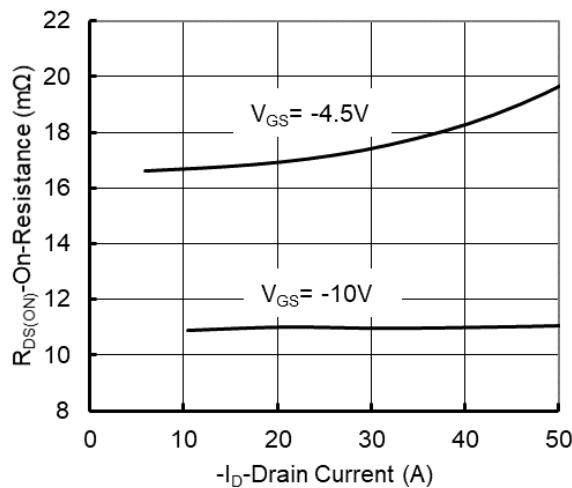
## Typical Characteristics



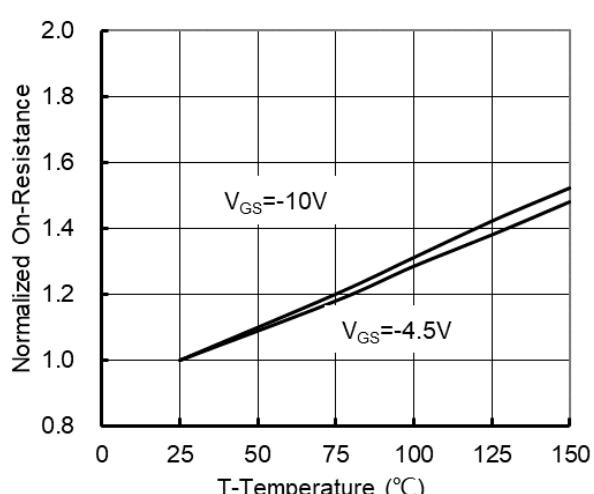
**Figure 1. Output Characteristics**



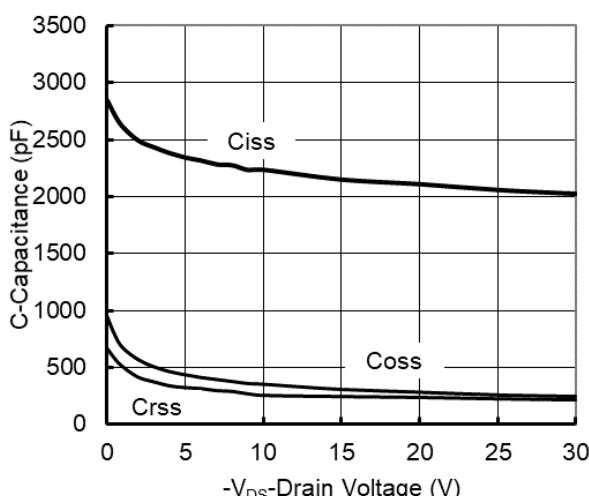
**Figure 2. Transfer Characteristics**



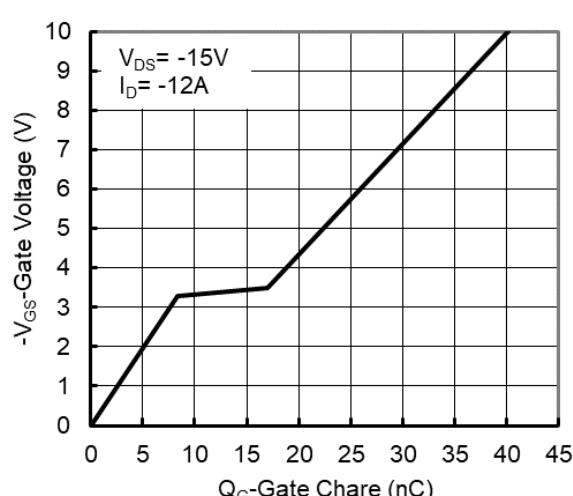
**Figure 3. On-Resistance vs. Drain Current and Gate Voltage**



**Figure 4. On-Resistance vs. Junction Temperature**

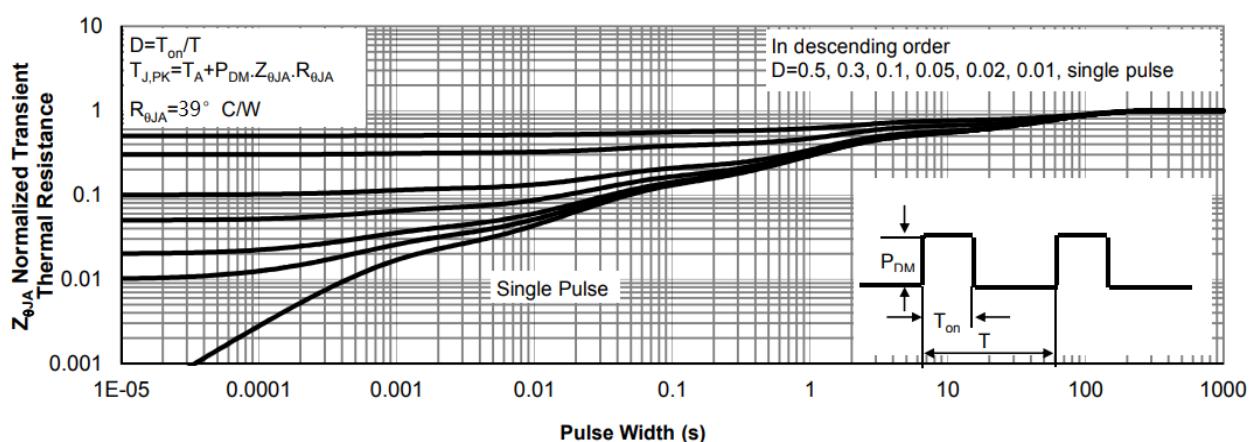
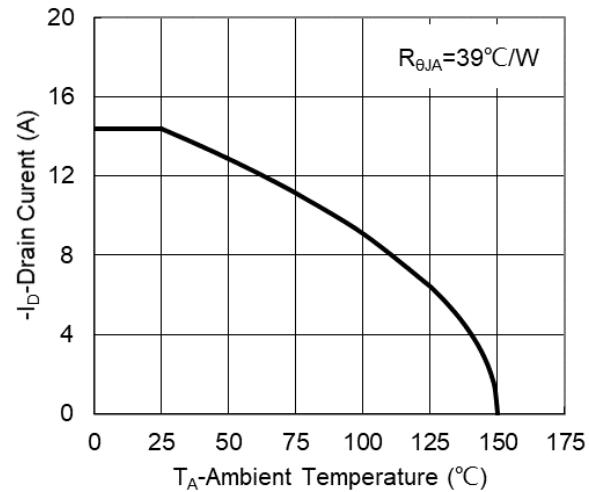
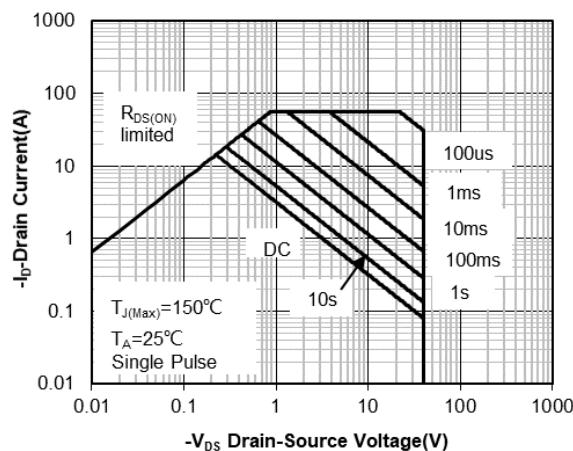


**Figure 5. Capacitance Characteristics**

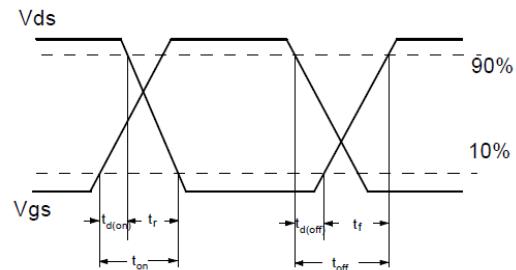
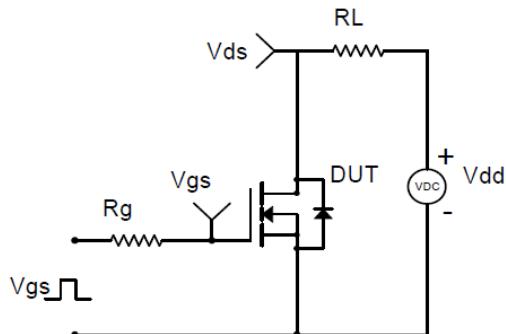


**Figure 6. Gate Charge**

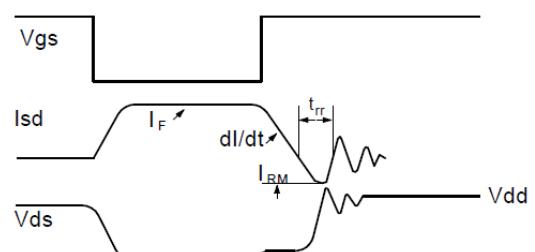
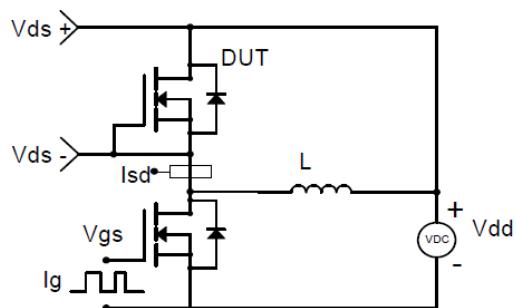
## Typical Characteristics



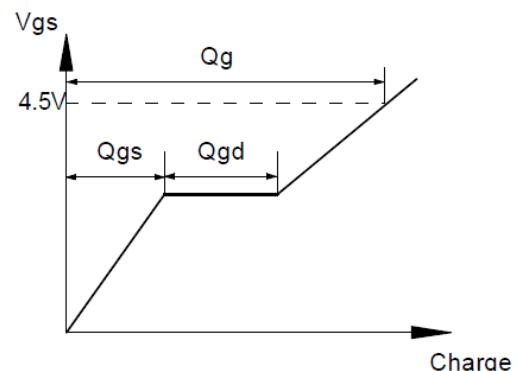
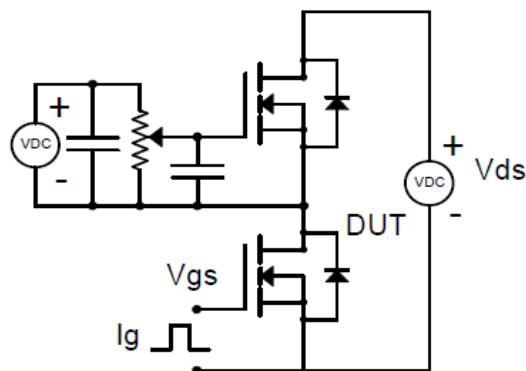
## Typical Characteristics



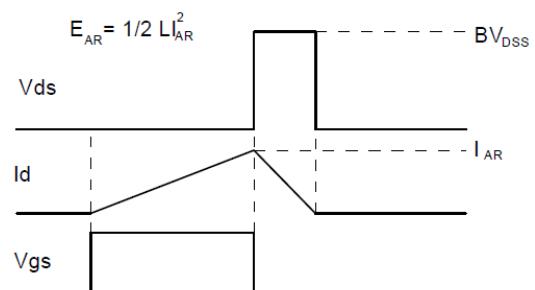
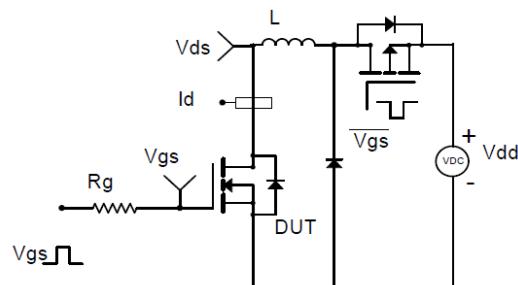
**Resistive Switching Test Circuit & Waveforms**



**Diode Recovery Test Circuit & Waveforms**

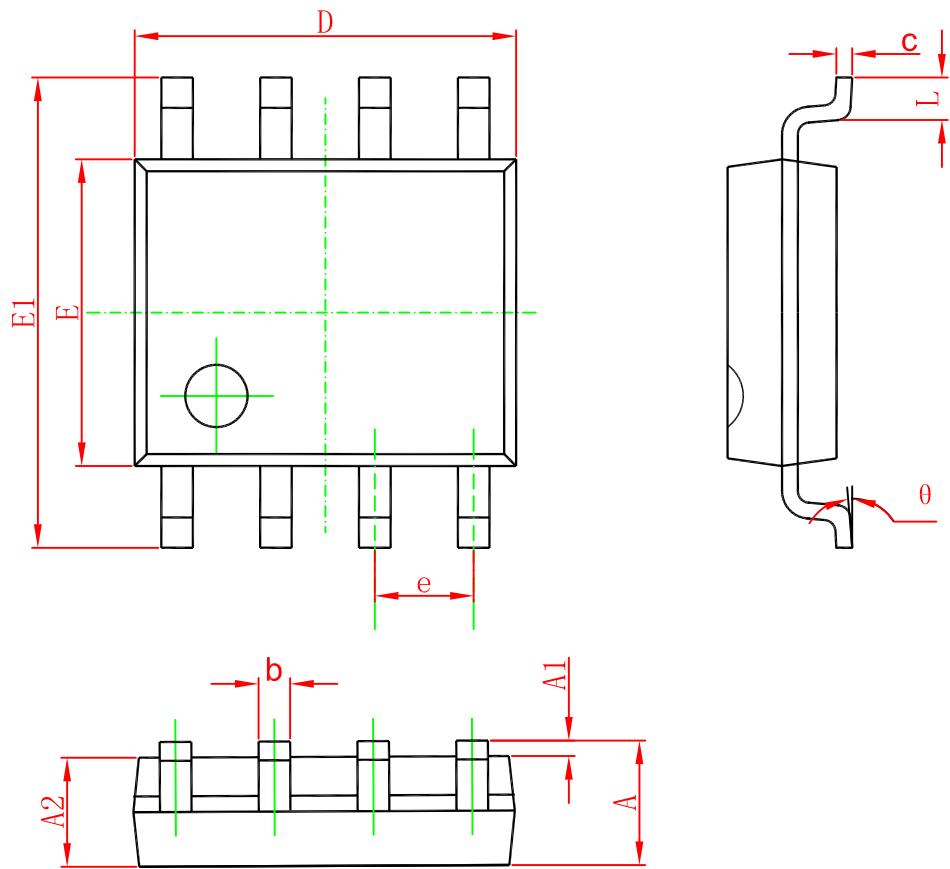


**Gate Charge Test Circuit & Waveform**



**Unclamped Inductive Switching (UIS) Test Circuit & Waveforms**

## SOP8 Package Information



Symbol	Dimensions In Millimeters		Dimensions In Inches	
	Min	Max	Min	Max
A	1.350	1.750	0.053	0.069
A1	0.100	0.250	0.004	0.010
A2	1.350	1.550	0.053	0.061
b	0.330	0.510	0.013	0.020
c	0.170	0.250	0.006	0.010
D	4.700	5.100	0.185	0.200
E	3.800	4.000	0.150	0.157
E1	5.800	6.200	0.228	0.244
e	1.270 (BSC)		0.050 (BSC)	
L	0.400	1.270	0.016	0.050
$\theta$	0°	8°	0°	8°